Hybrid Pulsed Laser Diode with Integrated Driver Stage 70 W Peak Power Version 1.2

SPL LL90_3



Features:

- · Low cost, small size plastic package
- · Integrated FET and capacitors for pulse control
- Strained InAIGaAs/GaAs QW-structures
- · High power large-optical-cavity laser structure
- Nanostack laser technology including multiple epitaxially stacked emitters
- The product qualification test plan is based on the guidelines of AEC-Q101-REV-C, Stress Test Qualification for Automotive Grade Discrete Semiconductors.
- High-speed operation (< 30 ns pulse width)
- Low supply voltage (< 20 V)

Applications

- · Range finding
- · Security, surveillance
- · Illumination, ignition
- · Testing and measurement

Notes

Depending on the mode of operation, these devices emit highly concentrated non visible infrared light which can be hazardous to the human eye. Products which incorporate these devices have to follow the safety precautions given in IEC 60825-1 "Safety of laser products".

Ordering Information

Туре:	Number of emitters	Peak wavelength	Peak output power	Ordering Code
		λ_{peak}	P _{opt}	
SPL LL90_3	3	905	70	Q65110A1009



Maximum Ratings (short time operation / kurzzeitiger Betrieb, $T_A = 25$ °C)

Parameter	Symbol	Values	Unit
Peak output power	P _{peak}	80	W
Charge voltage (V _G = 15 V)	V _C	20	V
Gate voltage	V _G	-20 20	V
Duty cycle	dc	0.1	%
Operating temperature	T _{op}	-40 100	°C
Junction temperature 1) page 7	T _j	105	°C
Storage temperature range	T _{stg}	-40 100	°C
Soldering temperature (t _{max} = 10 s)	T _s	260	°C

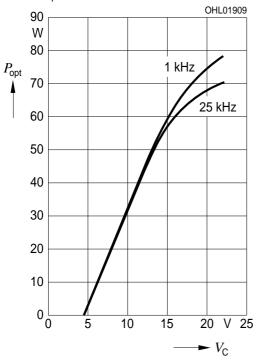
Characteristics (T_A = 25 °C)

Parameter	Symbol	Values		Unit	
		min	typ	max	
Emission wavelength ^{2) page 7}	λ_{peak}	895	905	915	nm
Spectral width (FWHM) 2) page 7	Δλ		7		nm
Peak output power ^{2) page 7}	P _{opt}	60	70	80	W
Charge voltage at laser threshold	U _{C, th}	4	4.5	5	V
Pulse width (FWHM) 2) page 7, 3) page 7	t _P	37	40	43	ns
Rise time ^{2) page 7, 3) page 7}	t _r	7	10	13	ns
Fall Time ^{2) page 7} , ^{3) page 7}	t _f	40	45	50	ns
Jitter (regarding trigger signal and optical pulse)	t _j		170	500	ps
Aperture size	wxh		200 x 10		μm x μm
Beam divergence (FWHM) parallel to pn-junction 2) page 7	ΘΙΙ	12	15	18	0
Beam divergence (FWHM) perpendicular to pn-junction 2) page 7	Θ_	27	30	33	0
Temperature coefficient of wavelength	Δλ / ΔΤ		0.3	0.33	nm / K
Thermal resistance	R _{th}		200		K/W
Switch on gate voltage	V_{Gon}		5		V



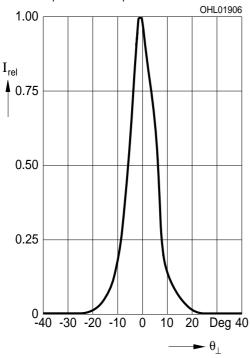
Optical Output Power vs. Charge Voltage

$$P_{opt} = f(V_C)$$
, $t_p = 30 \text{ ns}$



Far-Field Distribution Parallel to pn-Junction

$$I_{rel} = f(\Theta_{II}), P_{opt} = 70 \text{ W}, t_p = 30 \text{ ns}$$

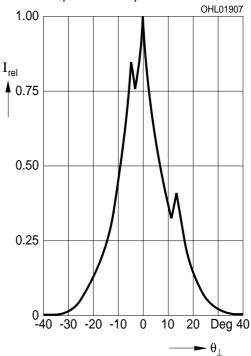


Relative Spectral Emission

Far-Field Distribution Perpendicular to pn-Junction

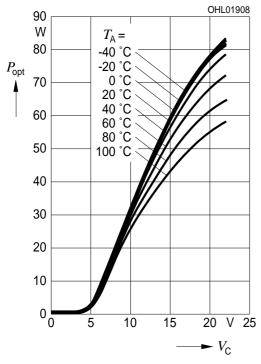
$$I_{rel} = f(\Theta_{\perp}), P_{opt} = 70 \text{ W}, t_p = 30 \text{ ns}$$

$$1.00$$



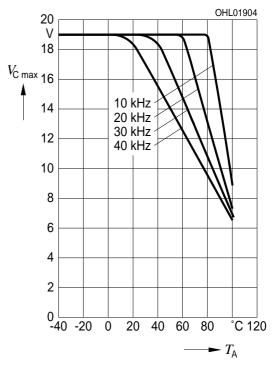
Optical Output Power vs. Charge Voltage

 $P_{opt} = f(V_C)$, tp = 30 ns, PRF = 1 kHz



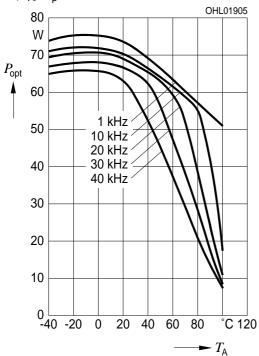
Max. Charge Voltage vs. Ambient Temperature

 V_{Cmax} = f(T_A), t_p = 30 ns, $V_C \le 19$ V, chip temp. ≤ 105 °C

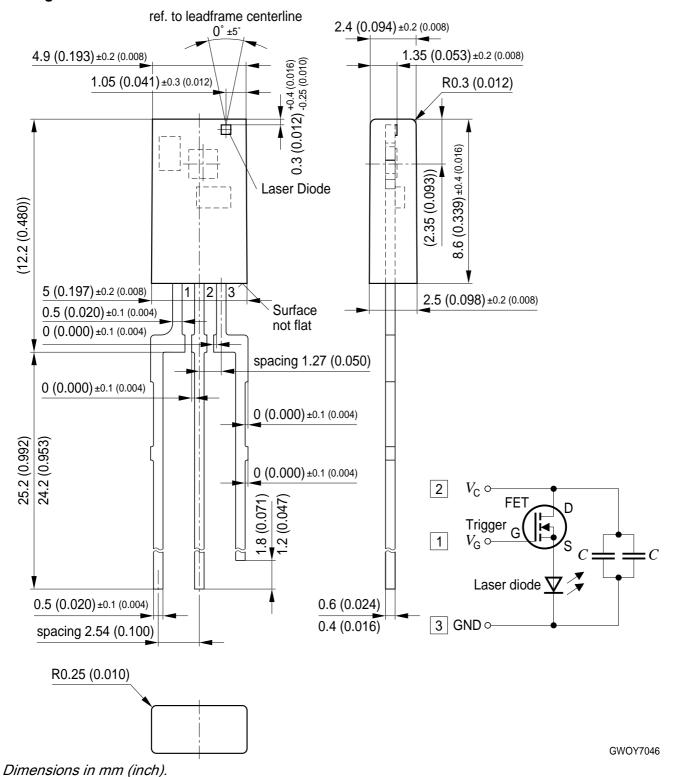


Peak Output Power at Max. Charge Voltage vs. Ambient Temperature

$$P_{opt} = f(T_A), t_p = 30 \text{ ns}$$



Package Outline



2017-05-24 5



Disclaimer

Language english will prevail in case of any discrepancies or deviations between the two language wordings.

Attention please!

The information describes the type of component and shall not be considered as assured characteristics.

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- **) Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health and the life of the user may be endangered.



Glossary

- 1) **Junction temperature:** Limited due to plastic package, not due to laser chip.
- ²⁾ **Standard operating conditions:** > 50 ns pulse width, 1 kHz pulse repetition rate, 18.5 V charge voltage, 15 V gate voltage and 25 °C ambient temperature. The laser is driven by the MOSFET driver Elantec EL7104C.

³⁾ **Switching speed:** Switching speed at gate depends on current and speed, charging the gate capacitance (typ. 300 pF) of the internal transistor. Reduced pulse widths, rise and fall times occur at trigger pulse widths < 50 ns. This also reduces the optical peak power.



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